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THE WORLDWIDE IC PACKAGING MARKET

2016 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis

- **Worldwide IC Packaging Market Forecasts, 2014–2020**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range

- **OSAT IC Packaging Market Forecasts, 2014–2020**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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The Worldwide IC Packaging Market, 2016 Edition

Synopsis

Integrated circuits are beyond question one of the most significant inventions of the 20th Century. Billions of ICs are manufactured every year, and are used in a vast range of products. In 2015, nearly 380 billion ICs were manufactured and shipped by semiconductor companies across the globe, and over the next five years, it is expected that the market will expand at a compounded annual growth rate of more than 4%.

At one time, the methods and technologies used to package and protect delicate integrated circuits were relatively simple. However, as IC devices themselves have become more powerful, the sophistication and complexity of IC packaging have also matured. Today, there are dozens of different types of packages in hundreds, even thousands of variations.

The Worldwide IC Packaging Market, 2016 Edition, a new report from New Venture Research (NVR) provides in-depth analysis of semiconductor devices and the IC packaging industry. Using extensively researched historical and current market trend data, the report examines the global IC packaging market, providing 5-year forecasts from a number of perspectives, including packaging type, I/O count, and application. Forecasts are provided for unit shipments, annual revenues and packaging pricing for 31 separate IC device types, as well as 14 major packaging categories comprised of 44 market segments. The report also includes an economic and major product overview of the global electronics industry, as well as a focused analysis of the Outsourced Semiconductor Assembly and Test (OSAT) industry segment.



The report is divided into seven chapters. Following an Introductory chapter (Chapter 1) and an Executive Summary (Chapter 2), the report presents an Economic Outlook and Worldwide Electronics Industry Forecast (Chapter 3). In Chapter 4, the report dives deeply into an examination of each Semiconductor product type, with forecasts provided in terms of packaging types, applications and major world regions. This is followed in Chapter 5 with detailed analysis of each packaging market segment, with forecasts provided in terms of IC device types and I/O count. The chapter also provides an overview of advanced packaging products and technologies. (For a much deeper analysis of advanced IC packaging markets and technologies, check out the companion report, *Advanced IC Packaging Technologies, Materials and Markets, 2016 Edition*.)

Chapter 6 extends NVR's long-term coverage of the OSAT market, a significant and significantly growing segment of the overall semiconductor market sector. This market segment is well worth targeted consideration. Already by 2015, the market penetration of OSATs was more than 50% of the total IC packaging market, and its dollar share is expected to expand to nearly two-thirds by 2020. To help you further assess this specialized group of companies, profiles of 41 OSAT competitors are provided in Chapter 7.

The Worldwide IC Packaging Market, 2016 Edition, continues NVR's leadership position in measuring the current status and future development of IC packaging. This report is an effective and economical tool for any company interested in competing in the semiconductor industry, as an aid in assessing these markets and for gaining an advantage in potential areas for their own growth. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is \$1500. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$1000 and a printed copy for \$250.

Jerry Watkins is an independent senior analyst with nearly 30 years of market research and consulting experience in the high-tech industry. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the office automation and telecommunications sectors and more recently in the merchant embedded computing and IC packaging industries. He holds two university degrees, a B.A. in History, as well as a M.A. in International Studies, and has lived and worked in the heart of Silicon Valley for over half of his adult life.

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Table of Contents

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Economic Outlook and Worldwide Electronics Industry Forecast

World and Semiconductor Overview

Not All Economies Recovering Equally;
Unrest Remains

World GDP

Global Electronics Market

Electronics Industry Summary Forecast

- Communications Markets, including: Cellular Handsets, LANs, DSL & Cable Modems, Carrier-class Equipment
- Computers Markets, including: PCs, Tablets, Servers, Storage Systems, Monitors, Printers
- Consumer Markets, including: TVs, Set-top Boxes, Digital Cameras, Personal Navigation Devices
- Industrial Markets, including: Process Control, Test & Measurements, Other Industrial
- Medical Markets, including: Medical Diagnostics, Therapeutic, Monitoring & Surgical
- Automotive Markets
- Commercial Aviation, Defense and Other Transportation Markets

Chapter 4: IC Packaging Market Analysis by Semiconductor Device

Worldwide Semiconductor Device Market

Total Market Forecasts

IC Function Forecasts

IC Application Trends

Covers: Consumer, Transportation, Computer Communications, Industrial & Other

IC Market Forecasts by Major World Regions

Market Forecasts by Device Type

Transistors

Processor Devices: MPUs, MCUs (4-bit, 8-bit, 16-bit, 32+-bit), DSPs

Memory Devices: DRAM, SRAM, Flash, ROM/EPROM, EEPROM

Logic Devices: Digital Bipolar, Standard Logic, Gate Arrays, Standard Cell & PLDs, Display Drivers & Touch Screen Controllers, Special Purpose Logic (Consumer, Computers, Communications, Automotive, Multipurpose & Other)

Analog Devices: Amplifiers & Comparators, Interfaces, Voltage Regulators & References, Data Converters, Application-Specific Analog (Consumer, Computers, Communications, Automotive, Industrial & Other)

Chapter 5: IC Packaging Overview and Total Worldwide Market Analysis

Overview

IC Package Families

Worldwide IC Packaging

Total IC Packaging Market Forecasts

IC Packaging Market by I/O Count

Package Pricing Trends

IC Package Families Forecasts

Transistor Outline Packaging Markets

Dual In-Line Package Markets

Small Outline Transistor Market

Small Outline Markets

Thin Small Outline Package Markets

Chip Carrier Markets

Quad Flat Pack Markets

Dual Flat Pack No Lead Markets

Quad Flat Pack No Lead Markets

Pin Grid Array Package Markets

Ball Grid Array Package Markets

Fine-Pitch Ball Grid Array Package Markets

Wafer-Level Packaging Markets

Direct Chip Attach Markets

Advanced IC Packaging

Multichip Packages

Fan-Out Wafer-Level Package (FOWLP)

Multirow QFN Packages

Flip Chip Interconnection

Through-Silicon Via Interconnect Solutions

Chapter 6: OSAT Market and Strategy Analysis

Outsourcing in the Semiconductor Market

OSAT Market Forecasts, including: *Unit Shipments, Revenues, Package ASP*

OSAT Market Leaders

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Table of Contents (continued)

Chapter 7 OSAT Company Profiles

3D Plus	Deca Technologies	Shinko Electric
ASE	FlipChip Int'l	Signetics Corp.
Advotech	Greatek Electronics	Sigurd
AIC Semiconductor	Hana Microelectronics	SPiL
Amkor Technology	HANA Micron	SPEL
Anst China	I2A Technologies	STATS ChipPAC
Azimuth	J-Devices	Tera Probe
Carsem	Jiangsu Changjiang Electronics	Tianshui Huatian Tech
Chant World Technology	Lingsen Precision	Unisem
China Wafer Level CSP	NANIUM	UTAC
ChipMOS	Nantong Fujitsu	Vigilant Technology
Cirtek	Nepes Corp.	Walton Advanced Eng.
CONNECTEC Japan	OSE	Xintec
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Publish Date: November 2016 - 495 Pages

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